



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Sectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-05-31
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ENYD*V526IL1	A	Z7GA	2018-05-31
Amount	UoM	Unit type	ST ECOPACK Grade	
5.5	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2.6x1.8x0.5	16	flat	
Comment	YD VFQFPN16 2.6x1.8x0.5 PITCH 0.4; MDF valid for STG3693QTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ENYD*V526L1				4999998.0	1000182.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.475	mg	supplier	die	Silicon (Si)	7440-21-3		0.451	mg	949474	82000
				supplier	metallization	Aluminium (Al)	7429-90-5		0.003	mg	6316	545
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	2105	182
				supplier	metallization	Tungsten (W)	7440-33-7		0.005	mg	10526	909
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	4211	364
				supplier	Passivation	Silicon Oxide	7631-86-9		0.013	mg	27368	2364
Leadframe	M-004 Copper and its alloys	1.012	mg	supplier	Alloy	Copper (Cu)	7440-50-8		0.980	mg	968379	178182
				supplier	Alloy	Chromium (Cr)	7440-47-3		0.003	mg	2964	545
				supplier	Alloy	Tin (Sn)	7440-31-5		0.003	mg	2964	545
				supplier	Alloy	Zinc (Zn)	7440-66-6		0.002	mg	1976	364
				supplier	coating	Palladium (Pd)	7440-05-3		0.001	mg	988	182
				supplier	coating	Gold (Au)	7440-57-5		0.001	mg	988	182
Die attach	M-015 Other organic materials	0.086	mg	supplier	glue	Treated silica	14808-60-7		0.013	mg	151163	2364
				supplier	glue	Glycol ethers	34590-94-8		0.020	mg	232558	3636
				supplier	glue	Metal oxide	1344-28-1		0.010	mg	116279	1818
				supplier	glue	Curing agent & hardener	23996-25-0		0.007	mg	81395	1273
				supplier	glue	Epoxy resins	67924-34-9		0.036	mg	418605	6545
Bonding wires	M-008 Precious metals	0.125	mg	supplier	wire	Gold	7440-57-5		0.125	mg	1000000	22727
Encapsulation	M-015 Other organic materials	3.803	mg	supplier	Molding Compound	Silica fused	60676-86-0		3.398	mg	893505	617818
				supplier	Molding Compound	Epoxy resin	29690-82-2		0.200	mg	52590	36364
				supplier	Molding Compound	Phenol resin	25068-38-6		0.200	mg	52590	36364
				supplier	Molding Compound	Carbon black	1333-86-4		0.005	mg	1315	909